Di Jiang

List of Publications by Year in descending order

14 papers	248 citations	1162889 8 h-index	1372474 10 g-index
14 all docs	14 docs citations	14 times ranked	336 citing authors

#	Article	IF	Citations
1	A flexible and stackable 3D interconnect system using growth-engineered carbon nanotube scaffolds. Flexible and Printed Electronics, 2017, 2, 025003.	1.5	6
2	Embedded Finâ€Like Metal/CNT Hybrid Structures for Flexible and Transparent Conductors. Small, 2016, 12, 1521-1526.	5.2	15
3	Flexible Multifunctionalized Carbon Nanotubesâ€Based Hybrid Nanowires. Advanced Functional Materials, 2015, 25, 4135-4143.	7.8	20
4	Tape-Assisted Transfer of Carbon Nanotube Bundles for Through-Silicon-Via Applications. Journal of Electronic Materials, 2015, 44, 2898-2907.	1.0	21
5	Vertically Stacked Carbon Nanotube-Based Interconnects for Through Silicon Via Application. IEEE Electron Device Letters, 2015, 36, 499-501.	2.2	44
6	Reliability of carbon nanotube bumps for chip on glass application. , 2014, , .		2
7	Carbon nanotube/solder hybrid structure for interconnect applications. , 2014, , .		0
8	Chemically vapor deposited carbon nanotubes for vertical electronics interconnect in packaging applications. , 2014, , .		2
9	Carbon nanotubes for electronics manufacturing and packaging: from growth to integration. Advances in Manufacturing, 2013, 1, 13-27.	3.2	22
10	Effect of substrates and underlayer on CNT synthesis by plasma enhanced CVD. Advances in Manufacturing, 2013, 1, 236-240.	3.2	2
11	Paper-mediated controlled densification and low temperature transfer of carbon nanotube forests for electronic interconnect application. Microelectronic Engineering, 2013, 103, 177-180.	1.1	30
12	Reliability of carbon nanotube bumps for chip on film application. , 2013, , .		0
13	Through-Silicon Vias Filled With Densified and Transferred Carbon Nanotube Forests. IEEE Electron Device Letters, 2012, 33, 420-422.	2.2	67
14	Formation of three-dimensional carbon nanotube structures by controllable vapor densification. Materials Letters, 2012, 78, 184-187.	1.3	17